

L Number	Hits	Search Text	DB	Time stamp
1	758	374/208.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 20:47
2	526	374/183.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 20:48
3	171	374/158.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 20:48
4	1109	600/549.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 20:48
-	719	374/208.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 14:51
-	501	374/183.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/03 12:13
-	1022	600/549.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 17:28
-	300	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and calibration	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 11:43
-	20	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and calibration and memory and (removable or detachable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/08 15:05
-	107	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and calibration and memory	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/08 16:58
-	27	"167876"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/08 17:01
-	14	"2183342"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/08 17:03

	3	"9813677"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/09 16:19
	18	"4008614"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/08 17:08
	22	"3318977"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/08 17:08
	0	(probe and tip and isolation and algorithm).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/09 10:25
	395	374/1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/09 16:15
	91	374/2.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/09 16:16
	53	374/3.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/09 16:16
	165	374/158.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/09 16:20
	26	"5347476"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/15 12:15
	2	5347476.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/15 12:49
	2	5794625.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/15 12:49
	4	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and EEPROM and encapsul\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/16 14:18

	3	"9813677"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/16 13:43
	159	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and resistant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/16 14:18
	74	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and resistant and seal\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/16 14:19
	1	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and overmold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/16 14:19
	119	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and encapsulated	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/16 14:20
	31	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and encapsulated and fluid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/16 14:20
	1	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and (fluid near resistant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 09:41
	3	"6179785"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/16 14:37
	22521	water adj resistant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/16 14:38
	184	(water adj resistant) and (electrical adj connector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 11:59
	17	(water adj resistant) and (electrical adj connector) and (encapsulated or overcoated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/16 14:52
	17	(water adj resistant) and (electrical adj connector) and (encapsulated or overcoat)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 11:42

	479	(water adj resistant) and thermometer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 11:43
	480	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and seal\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 11:45
	328	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and seal\$4 and (water or fluid or liquid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 11:55
	28	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and seal\$4 and (water or fluid or liquid) and module	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 11:55
	18553	(seal\$5 or coat\$3 or overcoat\$4) and (electrical adj connector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:00
	7168	(seal\$5 or coat\$3 or overcoat\$4) and (electrical adj (terminal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:02
	5350	(seal\$5) and (electrical adj (terminal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:02
	3128	(seal\$5) and (electrical adj (terminal)) and (fluid or water or liquid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:03
	49	(seal\$5) and (electrical adj (terminal)) and ((fluid or water or liquid) adj resistant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:07
	296	(seal\$5) and (electrical adj (contact)) and ((fluid or water or liquid) adj resistant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:14
	393	(electrical adj (contact)) and (water near resistant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:15
	0	(electrical adj (contact)) NEAR (water near resistant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:15

	60	(electrical adj (terminal)) and (water near resistant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:16
	0	(electrical adj (terminal)) NEAR (water near resistant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:16
	6	(terminal) NEAR (water near resistant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:18
	142	chip and overmold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:22
	2381	chip and (water adj (proof or resistan\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:23
	4675	circuit and (water adj (proof or resistan\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:23
	8	circuit adj (water adj (proof or resistan\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:27
	112	board adj (water adj (proof or resistan\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:56
	1	(circuit adj board) adj (water adj (proof or resistan\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 13:06
	1313	(circuit adj board) and (water adj (proof or resistan\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 13:07
	2	(circuit adj board) near (water adj (proof or resistan\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 13:08
	1	(circuit adj board) near (liquid adj (proof or resistan\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 13:14

	58	(circuit adj board) and (liquid adj (proof or resistant))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 13:10
	1372	(circuit adj board) and (overcoat\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 13:14
	892	(circuit adj board) and (overcoat\$4) and protect\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 13:16
	6	((circuit adj board) NEAR (overcoat\$4)) and protect\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 14:33
	0	((circuit adj board) NEAR (overcoat\$4)) and protect\$5 and memory	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 14:34
	213	(circuit adj board) and memory and (overcoat\$4) and protect\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 14:35
	48	(circuit adj board) and (memory adj chip) and (overcoat\$4) and protect\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:00
	14	(circuit adj board) and (memory adj chip) and (overcoat\$4) and protect\$5 and moisture	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:12
	63	"4821148"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:12
	176	(circuit adj board) and (connection or terminal) and (overcoat\$4) and protect\$5 and moisture	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:20
	7	(circuit adj board) and (EEPROM) and (overcoat\$4) and protect\$5 and moisture	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:21
	27	(water adj proof) and EEPROM	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:24

	3270	(water adj proof) and (circuit board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:18
	803	(water adj proof) and (circuit board) and terminal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:34
	150	(water adj proof) and (circuit board)and (overcoat\$3 or encapsulat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:40
	150	(water adj proof) and (circuit board) and (overcoat\$3 or encapsulat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:06
	344	(water adj proof) adj connector	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:15
	17	((water adj proof) adj connector) and (circuit adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:58
	83	(water adj proof) and (connector) and (overcoat\$3 or encapsulat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:08
	9	((water adj proof) adj (connector)) and (overcoat\$3 or encapsulat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:10
	10	((water adj proof\$3) adj (connector)) and (overcoat\$3 or encapsulat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:13
	10	"5527989"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:12
	2	"6376914"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:12
	10	((water adj proof\$3) adj (connector)) and (overcoat\$3 or encapsulat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:13

	12	(water adj proof) adj contact	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:16
	120	(water adj proof\$3) NEAR (circuit board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:25
	2	(water adj proof\$3) NEAR (circuit adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:25
	40	((water adj proof\$3) NEAR (connector)) and (coating or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:37
	0	((water adj proof\$3) NEAR (connector adj pin)) and (coating or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:27
	0	((water adj proof\$3) NEAR (connector adj pin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:28
	0	((water adj proof\$3) NEAR (connector adj contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:28
	18	((water adj proof\$3) and (connector adj contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:47
	86	((water adj proof\$3) and (contact adj terminal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:48
	733	374/208.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 17:21
	513	374/183.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 15:28
	169	374/158.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 15:29

-	1074	600/549.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 15:30
-	733	374/208.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 17:28
-	1074	600/549.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 17:34
-	450	600/549.ccls. and probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 17:35
-	218	600/549.ccls. and probe and (cover or sheath)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 17:35
-	411	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and (transparent or clear)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 09:58
-	244	(374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and (transparent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 09:58
-	284	(374/208.ccls. or 374/183.ccls. or 374/158.ccls. or 600/549.ccls.) and (transparent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 09:59
-	2	"20020181545"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 14:51
-	0	"20020181545" and (processor or microprocessor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 14:51
-	1	"20020181545" and (process\$3 or microprocess\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 18:42
-	2	"20020181545"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 19:35

-	20	"4572365"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 19:37
-	24	"4619271"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/23 20:47